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(72) Inventors; and

(75) Inventors/Applicants (for US only): **JOHNSON, Morgan**
[US/US]; 401 N. Tomahawk Island Dr., Portland, OR
97217 (US). **WEISS, Frederick, G.** [US/US]; PO Box
896, Newberg, OR 97132 (US).

(74) Agents: **REED, Julie L.** et al.; Marger Johnson & McCol-
lom PC, 210 SW Morrison St., Ste. 400, Portland, OR
97204 (US).

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(54) Title: ABOVE MOTHERBOARD INTERPOSER WITH PERIPHERAL CIRCUITS

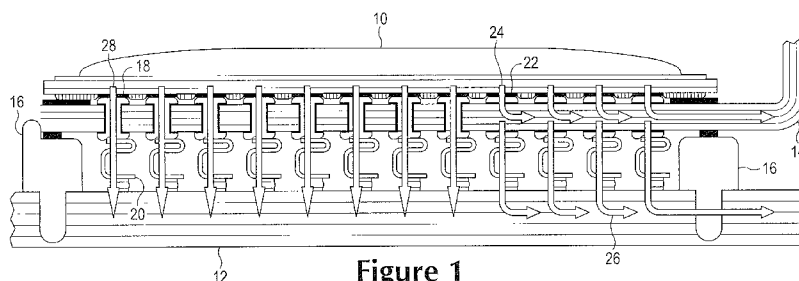


Figure 1

(57) Abstract: An interposer substrate includes an array of interconnects in the interposer substrate, the array of connectors arranged in accordance with an array of interconnects for a processor on a circuit substrate, at least one conductive trace in the interposer substrate in connection with at least one connector in the array of interconnects, the conductive trace arranged parallel to the interposer substrate such that no electrical connection exists between the connector in the interposer substrate and a corresponding one of the interconnects for the processor on the circuit substrate, and at least one peripheral circuit residing on the interposer substrate in electrical connection with the conductive trace.